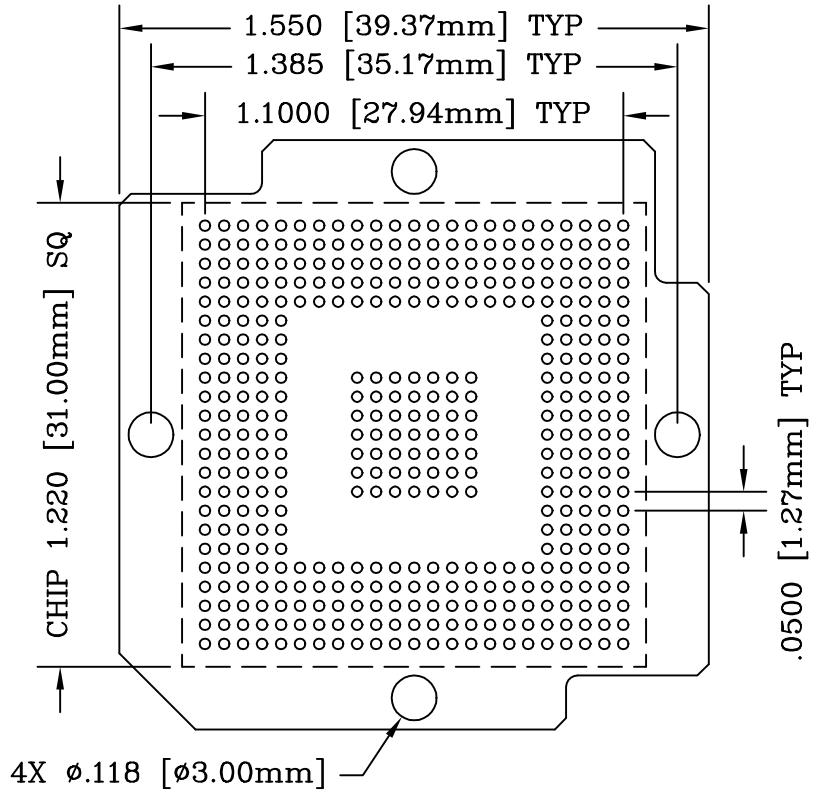
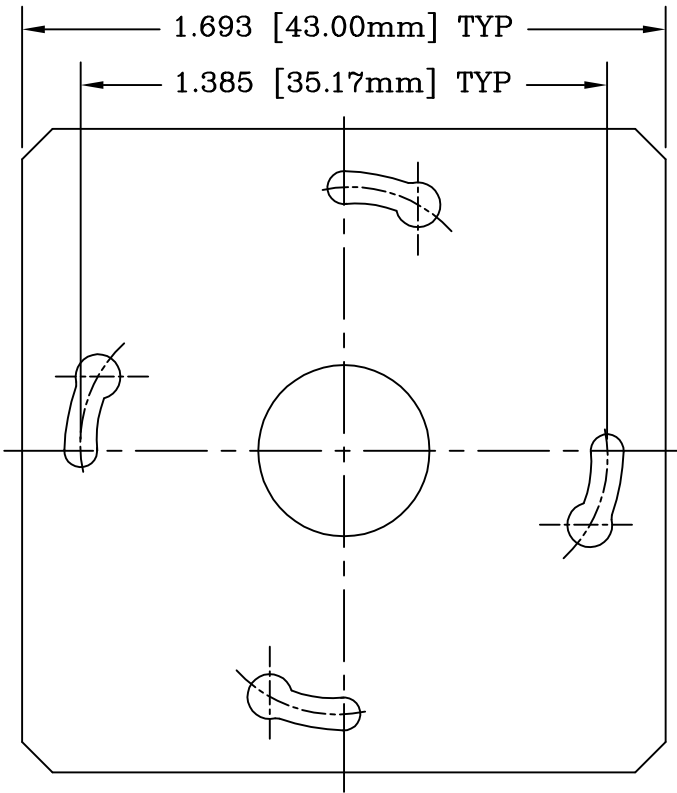


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	09/26/02	H.N.

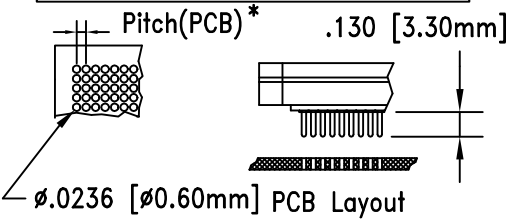
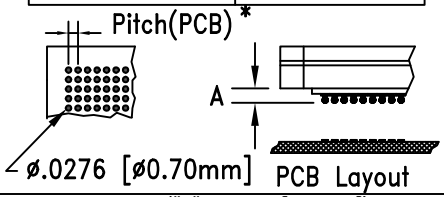
SKT1587  
DOD 41587



RECOMMENDED PAD LAYOUT

SOLDERTAIL STYLE	
REGULAR SMT STYLE	RAISED SMT STYLE
XX = (-SM)	XX = (-RC)
YY = (-30)	YY = (-29)

SOLDERTAIL = THRU HOLE STYLE
XX = (-ET)
YY = (-70)



30= standard SMD ("A" = .047 [1.20mm])  
29= raised SMD ("A" = .197 [5.00mm])  
BALL DIAMETER FOR:  
-29(RC) = .0217 [0.55mm]  
-30(SM) = .0217 [0.55mm]

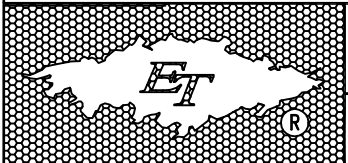
PIN DIAMETER FOR:  
-70(ET) = .0177 [0.45mm]

\* All Dimensions Are Nominal For A .050 [1.27mm] Pitch BGA Package

PACKAGE SPECIFICATIONS

PIN COUNT	= 409
LEAD PITCH	= 1.27mm
GRID SIZE	= 23X23
PACKAGE SIZE	= 31.00mm SQ

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



**Emulation Technology, Inc.**  
— VLSI and SMT ADAPTERS and ACCESSORIES —  
2344 Walsh Avenue, Bldg.F Santa Clara, Ca 95051  
TEL:(408)982-0660 FAX:(408)982-0664

SHEET: 1 OF 1	DATE: 09/26/02	REVISION: A	<b>ASSEMBLY DRAWING</b>
CHECKED: Perry Munroe	DRAWN: Huy Nguyen	ITEM: S-BGK-23-409-XX	DESCRIPTION: BPK-409-2BG023-YY
Scale 1:2	DO NOT SCALE DRAWING		